Nch 40V 80A Power MOSFET

V_{DSS}	40V
R _{DS(on)} (Max.)	5.6mΩ
I _D	±80A
P _D	78W

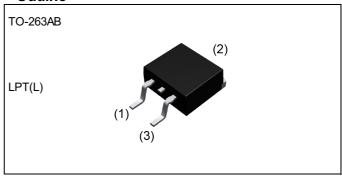
Features

- 1) Low on resistance
- 2) High power small mold package (LPTL)
- 3) Pb-free plating; RoHS compliant
- 4) 100% UIS tested

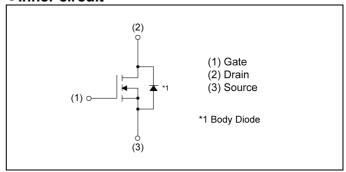
Application

Switching

Outline



•Inner circuit



Packaging specifications

er dekaging specifications					
	Packing	Embossed Tape			
Туре	Quantity (pcs)	1000			
	Taping code	TLL			
	Marking	RJ1G08CGN			

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	40	V
Continuous drain current	V _{GS} = 10V	I _D *1	±80	А
Pulsed drain current	I _{DP} *2	±160	А	
Gate - Source voltage	V _{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	30	Α	
Avalanche energy, single pulse	E _{AS} *3	35	mJ	
Power dissipation	P _D *1	78	W	
Junction temperature	T _j	150	°C	
Operating junction and storage temp	perature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Cymah al	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	1.6	°C/W

● Electrical characteristics (T_a = 25°C)

Darameter	Symbol Conditions -		Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = 1 \text{mA}$ referenced to 25°C		-	26.2	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V	1	1	1	μΑ	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	ı	ı	±500	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 500 \mu A$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I _D = 1mA referenced to 25°C	-	-4.9	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 80A	-	4.2	5.6	mO.	
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 40A	-	5.0	6.7	mΩ	
Gate resistance	R_{G}	f = 1MHz, open drain	-	3.4	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 5V, I _D = 40A	25	-	-	S	

^{*1} T_c =25°C, Limited only by maximum temperature allowed.

^{*2} Pw≦10µs , Duty cycle≦1%

^{*3} L \simeq 0.05mH, V_{DD} = 20V, R_G = 25 Ω , Starting T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C)

Darameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2410	-	
Output capacitance	C _{oss}	V _{DS} = 20V	-	370	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	135	-	
Turn - on delay time	t _{d(on)} *4	V _{DD} ≈ 20V,V _{GS} = 10V	1	17	1	
Rise time	t _r *4	I _D = 40A	1	9	ı	no
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 0.5\Omega$		70		ns
Fall time	t _f *4	$R_G = 10\Omega$	-	16	-	

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Canditions		Values			Unit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic	
Total gate charge	O *4		V _{GS} = 10V	-	31.1	-	
Total gate charge	Q _g *4	$V_{DD} \simeq 20V$		-	15.7	-	
Gate - Source charge	Q _{gs} *4	I _D = 40A	V _{GS} = 4.5V	-	6.0	-	nC
Gate - Drain charge	Q _{gd} *4			-	4.5	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Daramatar	Cumbal	Conditions		Values		
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Continuous forward current	I _S	T = 25°C	-	-	65	Α
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	160	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 65A$	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 50A, V _{GS} =0V	-	34	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	32	-	nC

Fig.1 Power Dissipation Derating Curve

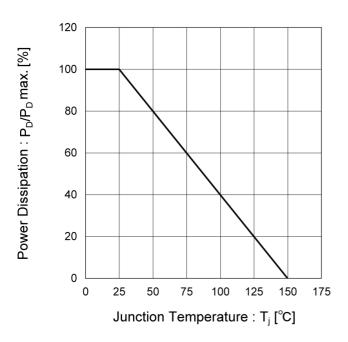
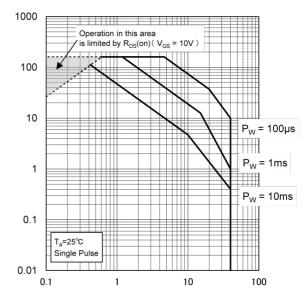


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

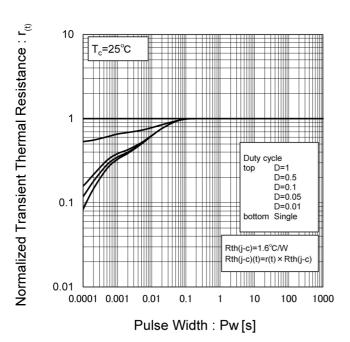


Fig.4 Single Pulse Maximum Power Dissipation

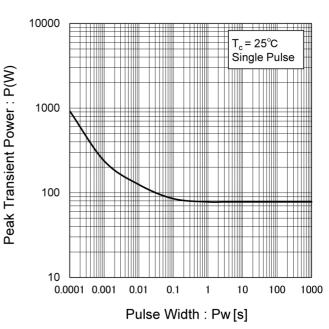
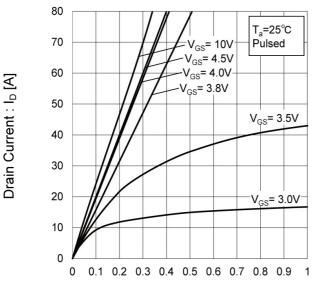
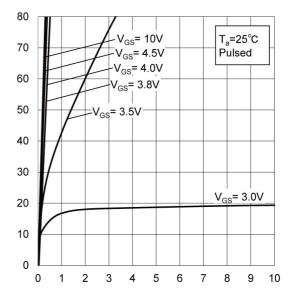


Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature

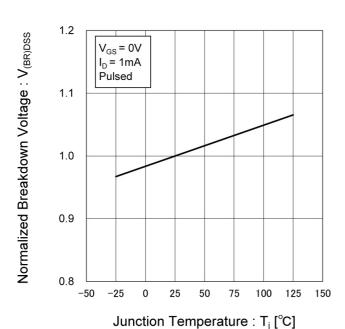


Fig.8 Typical Transfer Characteristics

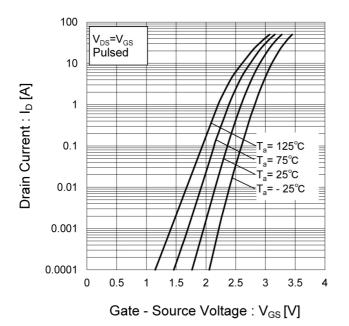
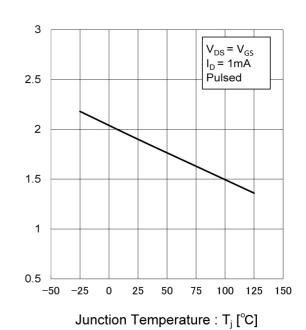


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage: VGS(th) [V]

Fig.10 Forward Transfer Admittance vs.
Drain Current

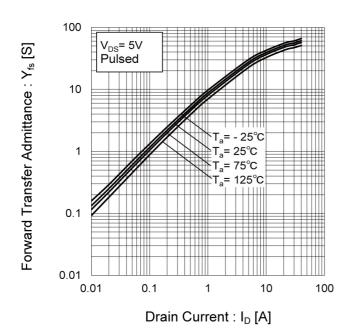


Fig.11 Drain Current Derating Curve

120 Drain Current Dissipation: I_D/I_Dmax. [%] 100 80 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

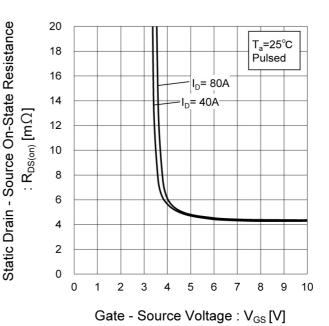


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

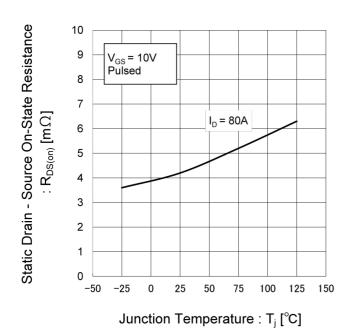


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

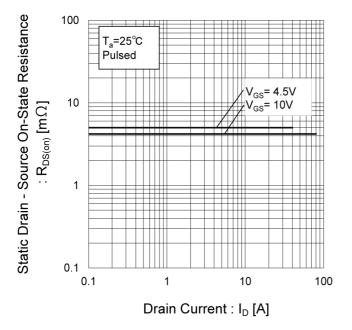


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

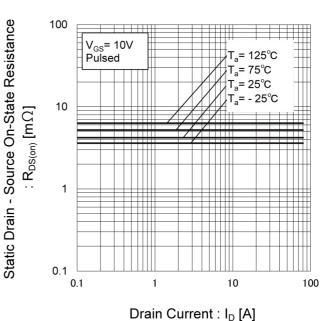


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

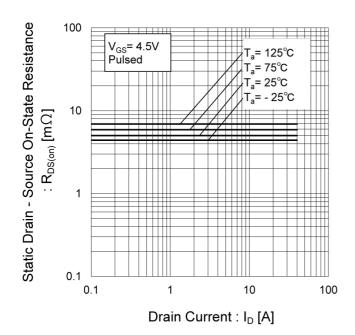


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

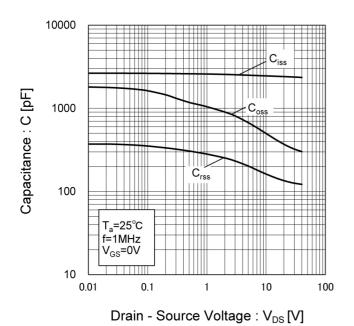


Fig.18 Switching Characteristics

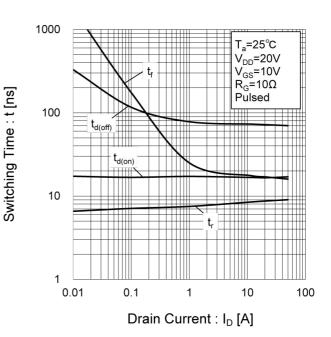


Fig.19 Typical Gate Charge

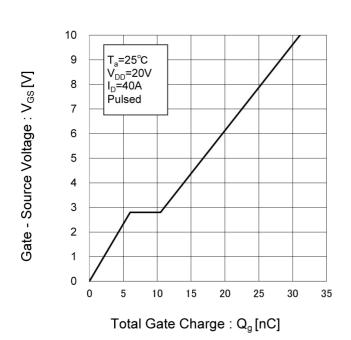
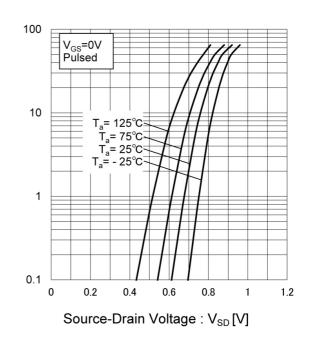


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

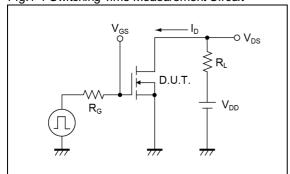


Fig.2-1 Gate Charge Measurement Circuit

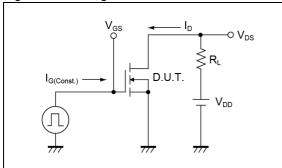


Fig.3-1 Avalanche Measurement Circuit

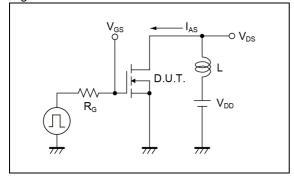


Fig.1-2 Switching Waveforms

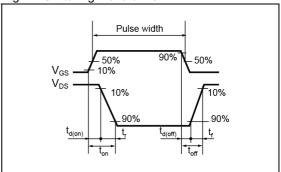


Fig.2-2 Gate Charge Waveform

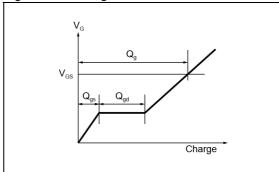
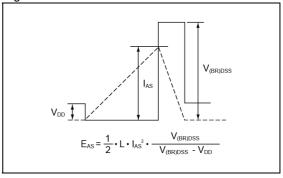
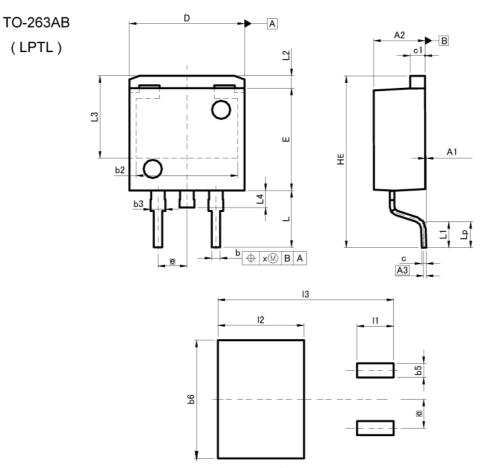


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	14.80	15.40	0.583	0.606
L	4.70	5.30	0.185	0.209
L1	2.10	2.70	0.083	0.106
L2	1.	10	0.0	43
L3	7.	25	0.2	85
L4	1.	50	0.0	59
Lp	2.60	2.00	0.102	0.079
х	-	0.25	_	0.010

DIM MILII		ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b5	(-	1.23	-	0.049
b6	-	10.40	1	0.409
11	-	3.20	-	0.126
12	-	7.55	-	0.297
13	i -	15.40	-	0.606

Dimension in mm/inches



Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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